

FKPF12N80

Application Explanation

- Switching mode power supply, light dimmer, electric flasher unit, hair drier
- TV sets, stereo, refrigerator, washing machine
- Electric blanket, solenoid driver, small motor control
- Photo copier, electric tool



Bi-Directional Triode Thyristor Planar Silicon

Absolute Maximum Ratings T_C=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DRM}	Repetitive Peak Off-State Voltage (Note1)	800	V 25

Symbol	Parameter	Conditions		Rating	Units
I _{T (RMS)}	RMS On-State Current	Commercial frequency, sine full wave 360° conduction, T _C =82°C		12	А
I _{TSM}	Surge On-State Current	Sinewave 1 full cycle, peak value,	50Hz	120	Α
ALC: Inches		non-repetitive		132	Α
I ² t	I ² t for Fusing	Value corresponding to 1 cycle of halfwave, surge on-state current, tp=10ms		72	A ² s
di/dt	Critical Rate of Rise of On-State Current	I _G = 2x I _{GT} , tr ≤ 100ns	111	50	A/μs
P_{GM}	Peak Gate Power Dissipation		150	5	W
P _{G (AV)}	Average Gate Power Dissipation	1 64. 12.	E val V	0.5	W
V _{GM}	Peak Gate Voltage			10	V
I _{GM}	Peak Gate Current	9/1/0		2	Α
TJ	Junction Temperature	With the second		- 40 ~ 125	°C
T _{STG}	Storage Temperature	P. Control of the con		- 40 ~ 125	°C
V _{iso}	Isolation Voltage	Ta=25°C, AC 1 minute, T ₁ T ₂ G teri case	minal to	1500	V

Thermal Characteristic

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
$R_{th(J-C)}$	Thermal Resistance	Junction to case (Note 4)	ı	-	3.0	°C/W

Electrical Characteristics $\rm T_C = 25\,^{\circ}C$ unless otherwise noted

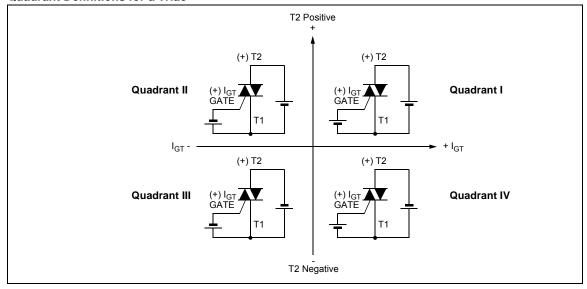
Symbol	Parameter		Test Condition		Min.	Тур.	Max.	Units
I _{DRM}	Repetieive Peak Off-State Cu	rrent	V _{DRM} applied		-	-	20	μА
V _{TM}	On-State Voltage		T _C =25°C, I _{TM} =17A Instantaneous measurement		-	-	1.5	V
	Gate Trigger Voltage (Note 2)	I	V _D =12V, R _L =20Ω	T2(+), Gate (+)	-	-	1.5	V
V_{GT}		II		T2(+), Gate (-)	-	-	1.5	V
		III		T2(-), Gate (-)	-	-	1.5	V
	Gate Trigger Current (Note 2)	I	V_D =12V, R_L =20 Ω	T2(+), Gate (+)	-	-	30	mA
I_{GT}		II		T2(+), Gate (-)	-	-	30	mA
		III		T2(-), Gate (-)	-	-	30	mA
V _{GD}	Gate Non-Trigger Voltage		T _J =125°C, V _D =1/2V _{DRM}		0.2	-	-	V
I _H	Holding Current		V _D = 12V, I _{TM} = 1A		-	-	50	mA
IL	Latching Current	I, III	V _D = 12V, I _G = 1.2I _{GT}		-	-	50	mA
		II			-	-	70	mA
dv/dt	Critical Rate of Rise of V_{DRM} = Rated, T_j = 125°C, Off-State Voltag Exponential Rise		· ',	-	300	-	V/µs	
(dv/dt) _C	Critical-Rate of Rise of Off-State Commutating Voltage (Note 3)				10	-	-	V/µs

- Notes:

 1. Gate Open
 2. Measurement using the gate trigger characteristics measurement circuit
 3. The critical-rate of rise of the off-state commutating voltage is shown in the table below
 4. The contact thermal resistance R_{TH(c-f)} in case of greasing is 0.5 °C/W

V _{DRM} (V)	Test Condition	Commutating voltage and current waveforms (inductive load)
FKPF12N80	 Junction Temperature T_J=125°C Rate of decay of on-state commutating current (di/dt)_C = - 6.5A/ms Peak off-state voltage V_D = 400V 	Supply Voltage Main Current Main Voltage (dv/dt) _C Time V _D

Quadrant Definitions for a Triac



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Typical Curves

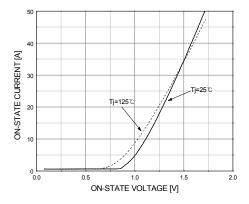


Figure 1. Maximum On-state Characteristics

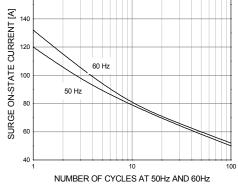


Figure 2. Rated Surge On-state Current

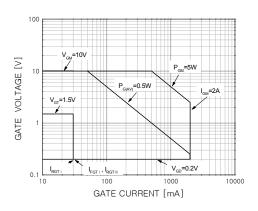


Figure 3. Gate Characteristics

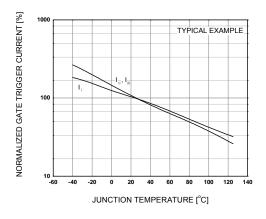


Figure 4. Gate Trigger Current vs Tj

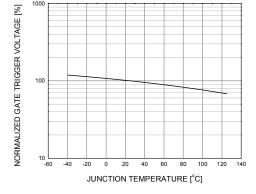


Figure 5. Gate Trigger Voltage vs Tj

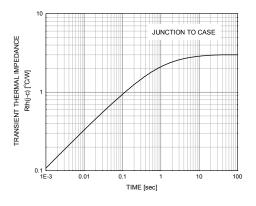


Figure 6. Transient Thermal Impedance

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Typical Curves (Continues)

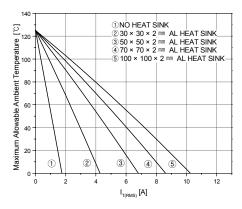


Figure 7. Allowable Ambient Temperature vs Rms On-state Current

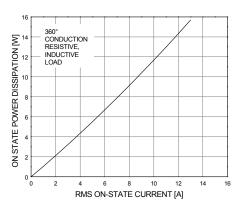


Figure 9. Maximum On-state Power Dissipation

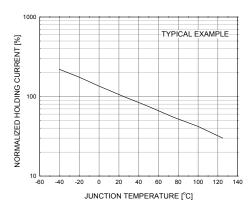


Figure 11. Holding Current vs
Junction Temperature

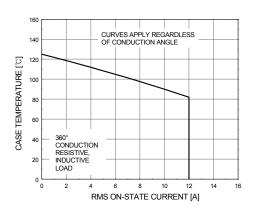


Figure 8. Allowable Case Temperature vs Rms On-state Current

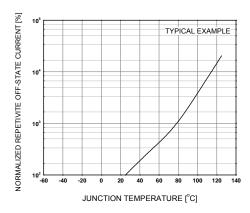


Figure 10. Repetitive Peak Off-state Current vs Junction Temperature

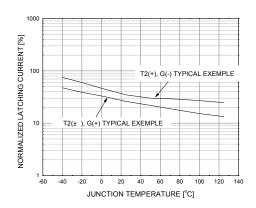


Figure 12. Laching Current vs
Junction Temperature

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Typical Curves (Continues)

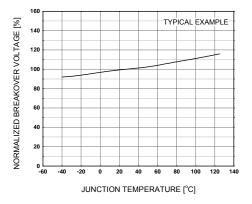


Figure 13. Breakover Voltage vs. Junction Temperature

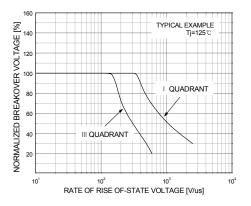


Figure 15. Breakover Voltage vs. Rate of Rise of Off-State Voltage

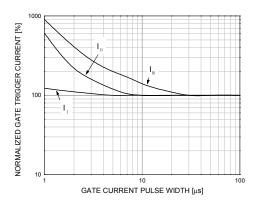


Figure 14. Gate Trigger Current vs.

Gate Current Pulse Width

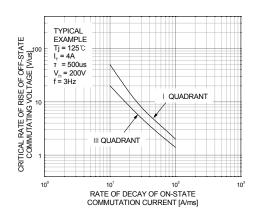
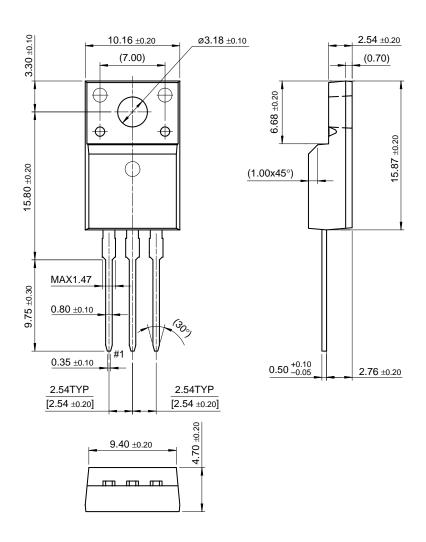


Figure 16. Commutation Characteristics

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Package Dimension

TO-220F



Dimensions in Millimeters

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